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(71) Applicant (for all designated States except US): MATSUSHITA ELECTRIC WORKS, LTD. [JP/JP]; 1048, Oaza-Kadoma, Kadoma-shi, Osaka, 5718686 (JP).

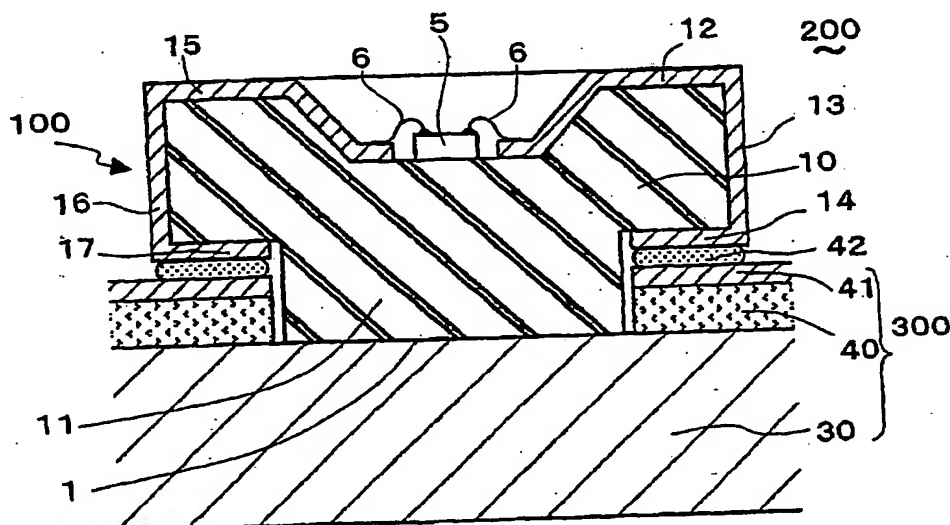
(72) Inventors; and

(75) Inventors/Applicants (for US only): HASHIMOTO, Takuma [JP/JP]; c/o MATSUSHITA ELECTRIC WORKS, LTD., 1048, Oaza-Kadoma, Kadoma-shi, Osaka, 5718686 (JP). SUGIMOTO, Masaru [JP/JP];

c/o MATSUSHITA ELECTRIC WORKS, LTD., 1048, Oaza-Kadoma, Kadoma-shi, Osaka, 5718686 (JP). YOKOTANI, Ryoji [JP/JP]; c/o MATSUSHITA ELECTRIC WORKS, LTD., 1048, Oaza-Kadoma, Kadoma-shi, Osaka, 5718686 (JP). NISHIOKA, Koji [JP/JP]; c/o MATSUSHITA ELECTRIC WORKS, LTD., 1048, Oaza-Kadoma, Kadoma-shi, Osaka, 5718686 (JP). IWAHORI, Yutaka [JP/JP]; c/o MATSUSHITA ELECTRIC WORKS, LTD., 1048, Oaza-Kadoma, Kadoma-shi, Osaka, 5718686 (JP). ISHIZAKI, Shinya [JP/JP]; c/o MATSUSHITA ELECTRIC WORKS, LTD., 1048, Oaza-Kadoma, Kadoma-shi, Osaka, 5718686 (JP). UCHINONO, Yoshiyuki [JP/JP]; c/o MATSUSHITA ELECTRIC WORKS, LTD., 1048, Oaza-Kadoma, Kadoma-shi, Osaka, 5718686 (JP). MUTO, Masahide [JP/JP]; c/o MATSUSHITA ELECTRIC WORKS, LTD., 1048, Oaza-Kadoma, Kadoma-shi, Osaka, 5718686 (JP). MORI, Satoshi [JP/JP]; c/o MATSUSHITA ELECTRIC WORKS, LTD., 1048, Oaza-Kadoma, Kadoma-shi, Osaka, 5718686 (JP).

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(54) Title: LIGHT-EMITTING DEVICE



(57) Abstract: A light-emitting device (200) has a submount (100) and a plate for heat transfer (300) having a metallic plate (30). The submount (100) has a mount base (10), at least one light-emitting diode chip (5) mounted thereon and electrically conducting lines (12-17) formed on the mount base (10) to be connected electrically to the light-emitting diode chip (5). A first plane (11) of the mount base (10) of the submount (100) is bonded thermally to the first plate (300). For example, the plate is a circuit board having a metallic plate (30), and the submount (100) is bonded thermally to the metallic plate (30) of the one of the at least one plate (300). In an example, a second plate for heat transfer is also bonded thermally to a second plane of the mount base (100) for providing a plurality of heat transfer paths.



KIMURA, Hideyoshi [JP/JP]; c/o MATSUSHITA ELECTRIC WORKS, LTD., 1048, Oaza-Kadoma, Kadoma-shi, Osaka, 5718686 (JP).

(74) **Agents:** KAWAMIYA, Osamu et al.; AOYAMA & PARTNERS, IMP Building, 3-7, Shiromi 1-chome, Chuo-ku, Osaka-shi, Osaka, 5400001 (JP).

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